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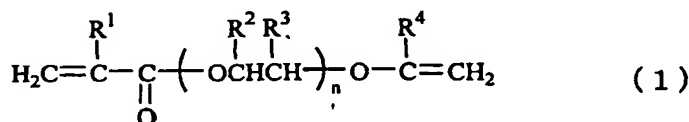
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(54) Title: **RADIATION-CURABLE LIQUID RESIN COMPOSITION**



(57) Abstract: The invention relates to a radiation -curable liquid resin composition comprising: (A) 20-90 wt% of a urethane (meth)acrylate oligomer, and (B) 1-35 wt% of - a monomer shown by the following formula (1), wherein R<sup>1</sup> represents a hydrogen atom or a methyl group, R<sup>2</sup> and R<sup>3</sup> individually represent a hydrogen atom or an alkyl group having 1-4 carbon atoms, R<sup>4</sup> represents a hydrogen atom or a methyl group, and n represents an integer of 1-6, or - a monomer including a hydroxyl group.